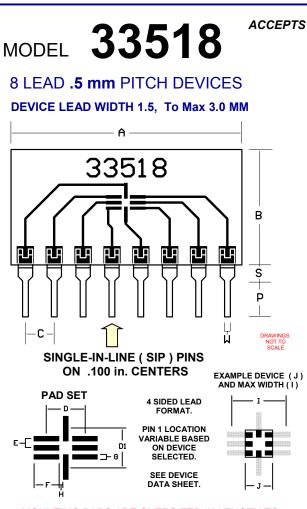
SURFBOARDS®

THE BREADBOARDING MEDIUM FOR SURFACE MOUNT TM

33000 SERIES APPLICATION SPECIFIC ADAPTERS IDS33518



MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING. SEE WEBSITE FOR SOLDERING SUGGESTIONS

BOARD SPECIFICATIONS



EC 2002/95

BOARD MATERIAL: .8mm, +-.13mm .031in+-..005 in. Thick G-10 FR-4 Glass Epoxy or equivalent. **CIRCUITS:** 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +- .5mm .020in.

TOLERANCES: If not noted are +- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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> CAPITAL ADVANCED TECHNOLOGIES, INC. CAROL STREAM, INLINOIS. USA PHONE 630-690-1696 FAX 630-690-2498 WWW.CapitalAdanced.Com



PARTIAL LISTING

FAIRCHILD 8LD,MICROPAK 1.6MM SQ.
ON SEMI ULLGA8 1.5x1.5,0.5P

UQFN8 1.5x1.5,0.5P UQFN8 1.6x1.6,0.5P

TEXAS INST. RSE (S-PQFP-N8) UQFN RUG (S-PQFP-N8)

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

Feature Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers.

Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

	JUST ADD PARTS AND PLUG-IN ™			D
	FIG.	мм	IN.	NOTE:
	Α	20.32	.800	BOARD WIDTH +5mm .020in.
))	в	10.16	.400	BOARD HEIGHT +5mm .020in.
	С	2.54	.100	SIP PIN SPACE +20mm .008in.
	D, D1	2.1	.083	PAD CENTERLINE
	Е	.5	.020	DEVICE LEAD PITCH
	F	1.4	.055	PAD LENGTH
	G	.3	.012	PAD WIDTH
	Н	.2	.008	GAP
	Ξ	3.0	.118	MAX LEAD WIDTH
	J	1.5	.059	TYPICAL LEAD WIDTH
	Р	3.3	.130	LENGTH FROM SHOULDER +5mm .020in.
F	S	1.57	.062	PIN SHOULDER HEGHT
í	w	.5	.020	PIN WIDTH